

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("20010049204").PN.	US-PGPUB	OR	OFF	2006/01/09 11:24
L2	1	("6009890").PN.	US-PGPUB; USPAT	OR	OFF	2006/01/09 11:24
L3	2415	(134/902).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L4	4	"134"/\$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24
L5	4	"396"/\$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24
L6	14	"118"/\$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24
L7	14	("4408560" "4693777" "4715392" "4828878" "5158616" "5297568" "5314509" "5379784" "5381808" "5431179" "5482068" "5485644" "5520744" "5795405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/09 11:24
L8	10	("6009890").URPN.	USPAT	OR	ON	2006/01/09 11:24
L9	539	(134/133).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L10	487	(134/134).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24

L11	166	(134/44).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L12	699	(134/56R).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L13	234	(118/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L14	2440	(118/500).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L15	1499	(118/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L16	398	(414/414).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 11:24
L17	5	"414"/\$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24
L18	3	("5899690" "5915910" "6051349").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/09 11:24
L19	10	(stack) and (semiconductor near3 wafer) and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24

L20	21	(stack) and (semiconductor near3 wafer) and (substrate near2 detector) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:24
L21	146	(stack) and (semiconductor near3 wafer) and (substrate near2 sensor) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:26
L22	11	(("6171403") or ("6517784") or ("6397582") or ("6883305") or ("6761178") or ("6769855") or ("6678081") or ("6811618") or ("6823659") or ("6857838") or ("6841511")).PN.	US-PGPUB; USPAT	OR	OFF	2006/01/09 11:24
L23	1	("6051349").PN.	USPAT	OR	OFF	2006/01/09 11:26
L24	1091	carrier with transfer with device with control	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:29
L25	0	carrier with transfer with device with control and ("118"/\$.ccls)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:30
L26	0	(carrier with transfer with device with control) and ("427"/\$.ccls)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:30
L27	12	(carrier with transfer with device with control) and (semiconductor and coating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/09 11:30